

**Amendments to the Specification:**

Please replace the first paragraph on page 5 with the following amended paragraph:

B | [Fig. 1 is a] Figs. 1a and 1b are vertical sectional [view] views of a pair of spaced large substrates, where Fig. 1a is a view of the substrates prior to their attachment, and Fig. 2b is a view showing [having] the liquid polymer of the present invention supported by the lower substrate and in contact with the upper substrate prior to compressing the pair of spaced large substrates and causing the liquid polymer to flow (i.e. to squeeze flow) towards the perimetric edges of the lower and upper substrates;

Please replace the paragraph starting as the third paragraph on page 6 and continuing on page 7 with the following amended paragraph:

B2 | Therefore, recapitulating as depicted in [Fig. 1,] Fig. 1a, lower substrate 12 has conductor pads 18 and solder bumps 19 that oppose conductor pads 20 of upper substrate 14. As shown in Fig. 1b, a measured amount of liquid polymer 16 is dispensed at specified location or locations on the lower substrate 12. The upper substrate 14 is lowered onto the lower substrate 12, during which it comes in contact with the dispensed polymer 16 and forces the same to move outwards through squeeze flowing. At completion of substrate joining (i.e., when conductor pads 18 and 20 are in contact for reflowing solder bumps 19 as seen in Fig. 2), the joined assembly 10 goes through a heating cycle, well known to those skilled in the art, to form electrically conducting joints 31 (i.e., the joining together of conductor pads 18 and 20 with the assistance of solder bumps 19) and to cure the polymer 16. As shown in Fig. 2, the polymer 16 after curing is an integral part of the joined assembly 10.